

Characterization of advanced detector and electronic devices performed at RBI

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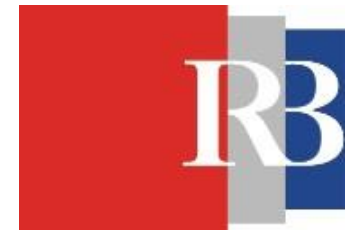
^c High Energy Physics group at RBI

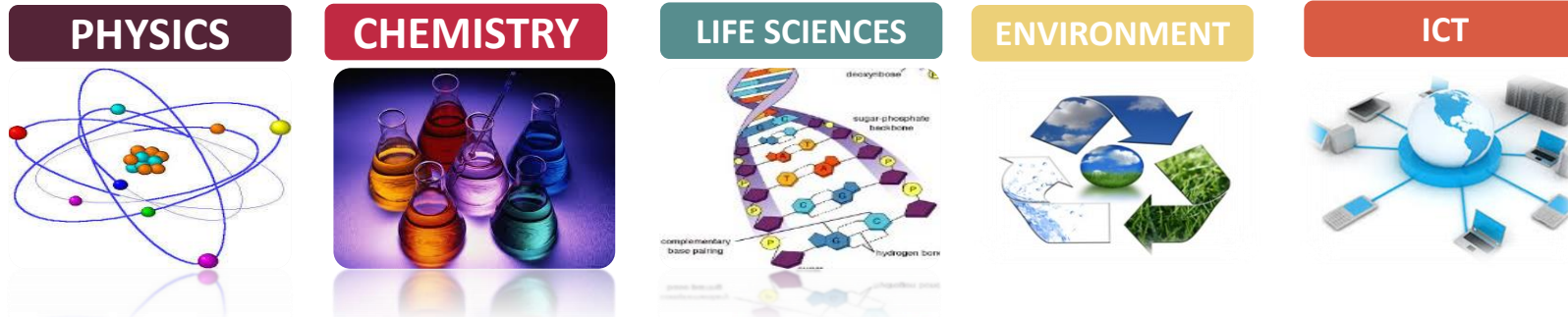
^d Radiation Chemistry and Dosimetry Laboratory at RBI

^e Electronic Engineering Department of School for Engineering in University of Seville, Spain



CDSE
Centar za detektore, senzore i elektroniku





900 employees of which 360 permanent, 290 Post Doctoral and PhD students

5 % of Croatian
researchers

~ 50 % of Croatian
Horizon 2020

15 % of Croatian
publications

30 % of Croatian
top publications

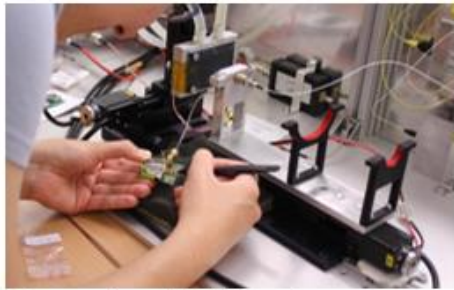
Mission:

Excellent science
Strong involvement in higher education
Leading contribution to the growth of the national economy

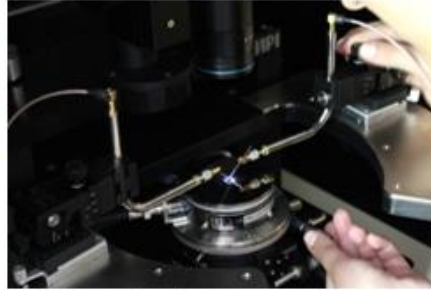
Vision:

Croatian centre of scientific excellence
Recognized research institution at international level

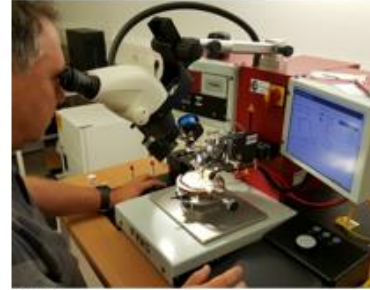
R&D Infrastructure at the CDSE



Scanning TCT setup



Probe station



Wire bonder



ColdBox setup

Legacy Infrastructure

- Accelerator Complex – Largest Experimental Complex in Croatia
- Gamma irradiation facility – 2PBq 60Co
- Neutron generator



6.0 MV EN Tandem Van de Graaff accelerator



1.0 MV HVE Tandetron accelerator



Experimental hall

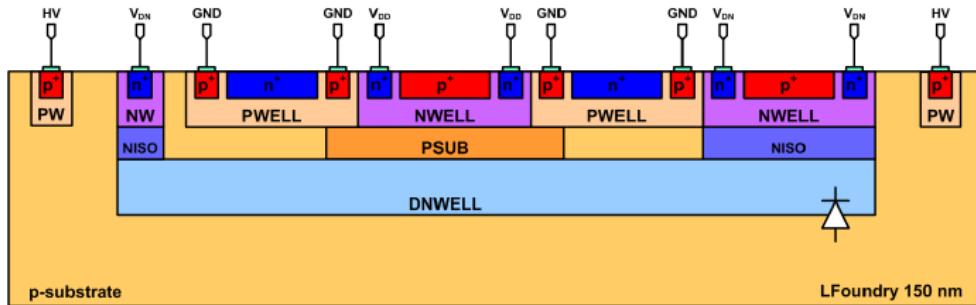
At RBI Material Physics and Chemistry Department

- Large selection of spectroscopic tools (PL, DLTS, Raman etc)

Radiation effects in Sensors and Electronics

Any Monolithic Detector means you need to test for Radiation Damage (CCE, etc) but also testing for Ionization Damage (TID) and Single Event Effects:

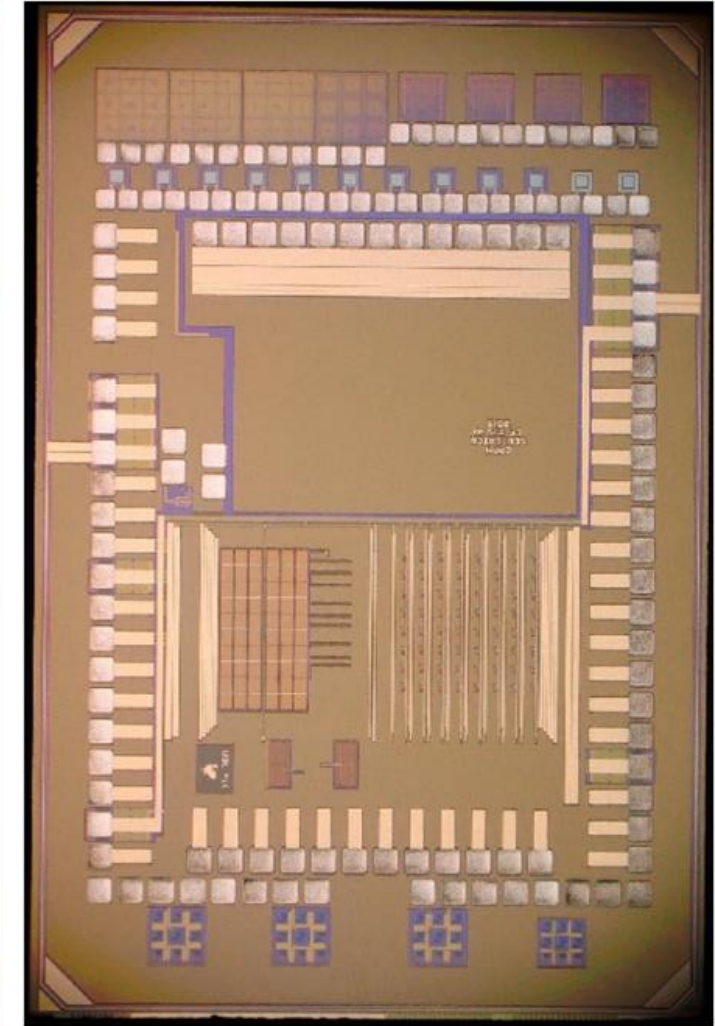
Electronics and Detectors embedded in the same crystal



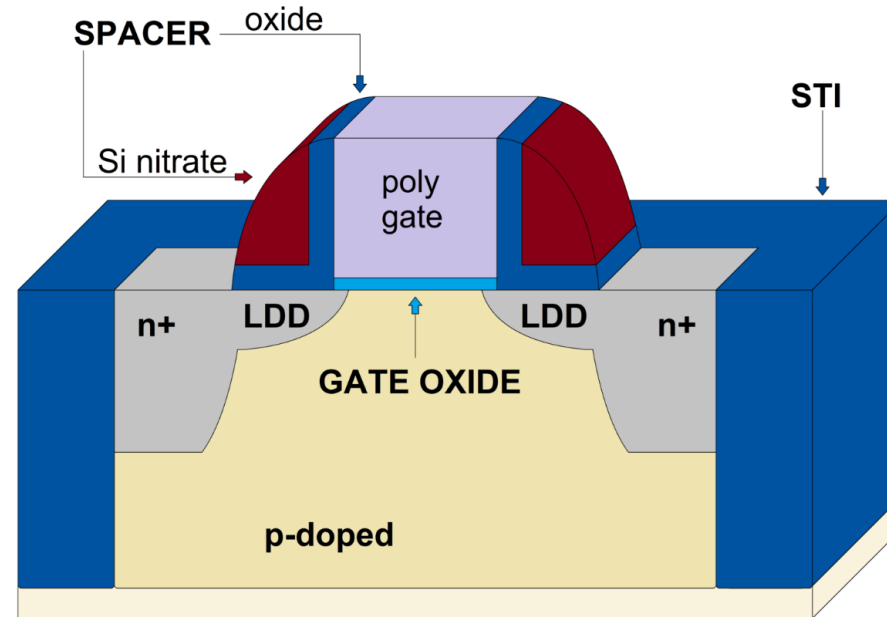
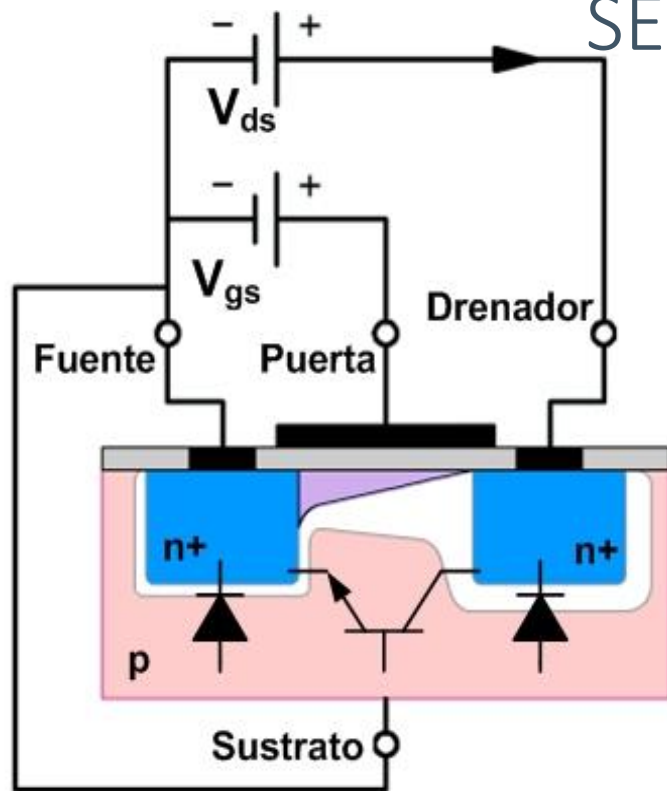
Pixel Cross-Section



RD50 – HVCMOS MPW2 Chip



SEE and Total Dose Overview (65nm)



Shallow Trench Isolation (STI): useful to isolate adjacent devices.

Spacers: Needed to create the Lightly Doped Source/Drain (LDD) extensions.

Body Diodes: As they are reverse polarized they act as Non-intended particle detectors. It means Single Event Effect (SEE)

Small W

Large W

STI-Related Effects

Small L

Large L

Spacers-Related Effects

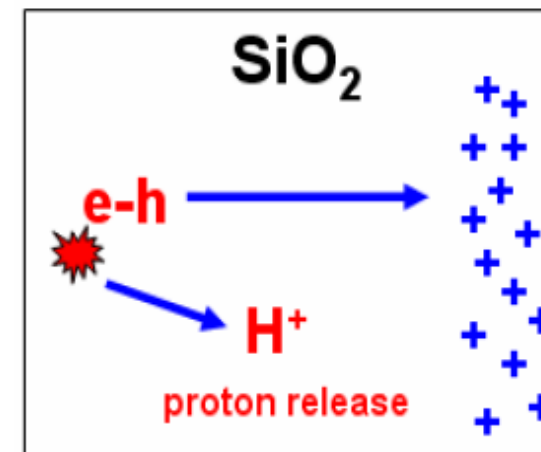
Take into account the irradiator Dose Rate

Under **high dose rate** there is a high generation of electron-hole pairs. The holes are forced to the interface by positive charge voltage, while the electrons are swept away into the gate. The buildup of holes at the interface form a positive charge barrier and repel the generated protons (H^+), keeping them away from forming interface states at channel interface. They will recombine

ELDRS (Enhanced Low Dose Rate Sensitivity)

Under **low dose rate** there is a low generation of electron-hole pairs. The holes are forced to the interface by positive charge voltage, while the electrons are swept away into the gate. The trapped hole buildup is much lower. The repelling force of the trapped holes is low enough to allow the H^+ to migrate to the interface forming interface states.

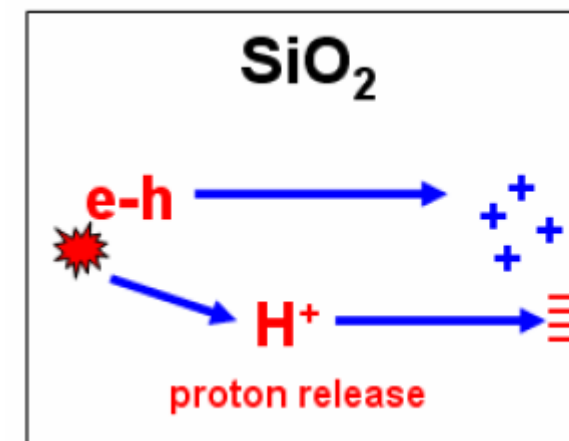
Low Dose Rate means more Interface Traps



High dose rate

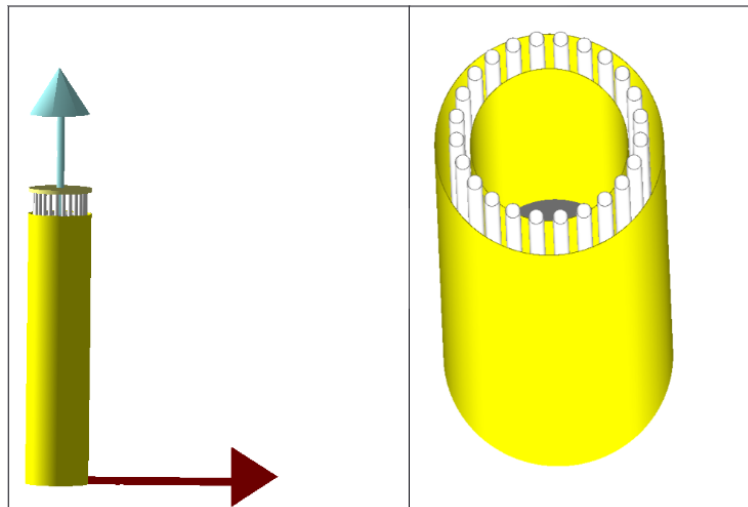
hole trapping (E')
+ electrostatic barrier

Rashkeev et al., IEEE TNS, 2002



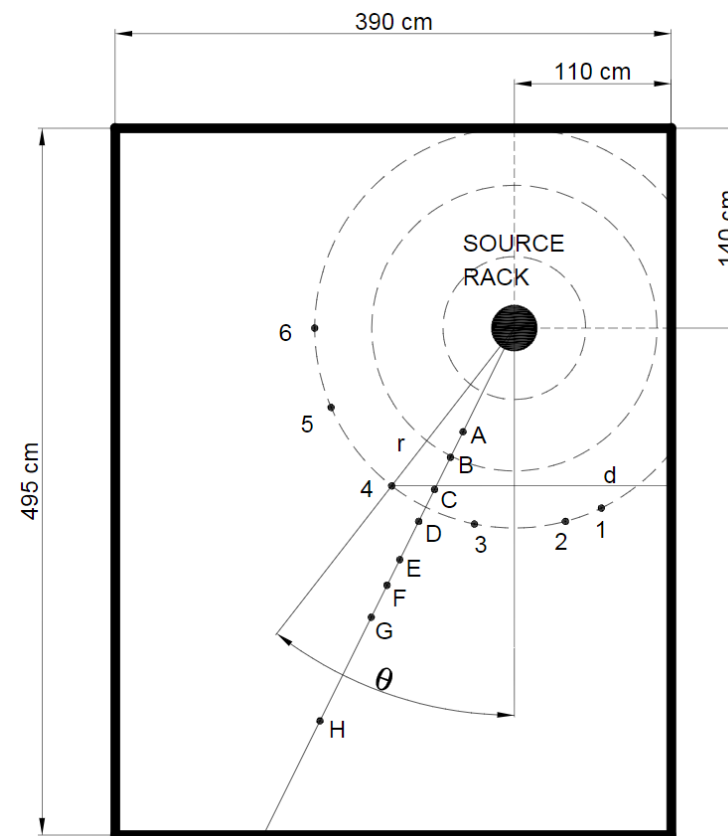
Low dose rate

hole trapping (E')
interface defect formation (P_b)



- Isotope life time – 5.27 years
- Main decay mode – 2 photons (1.17 MeV and 1.33 MeV)
- The source consist of 24 rods with 20 cm active cobalt pencils
- Total activity of the source is 1.8 PBq
- Smaller samples could be placed in the center of the cylinder where the dose rate is about 2.1 Mrad/h
- A dose of 34 krad/h can be delivered at the corner of the room or 1.2 m from the center of the source

⁶⁰Co irradiation chamber





Goals and Tasks

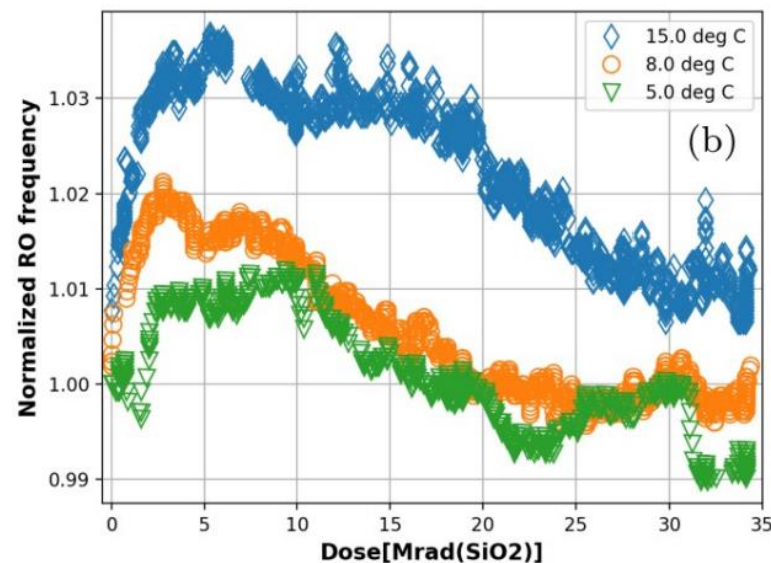
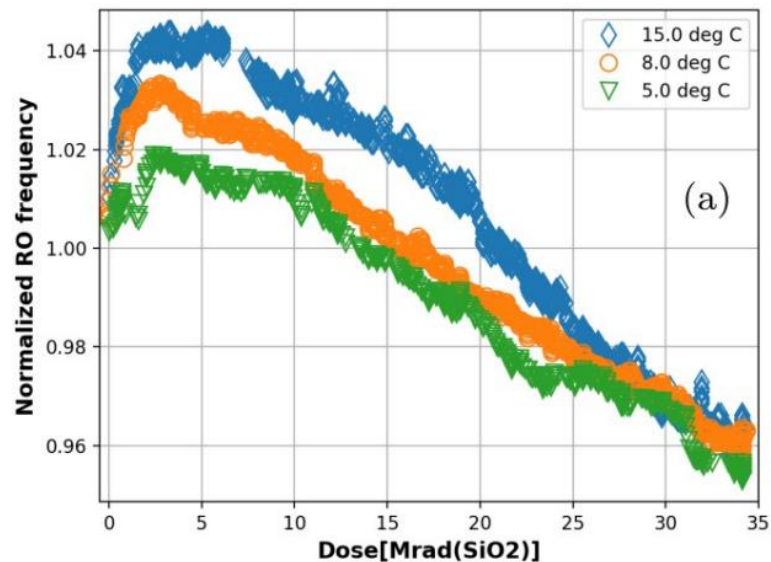
- Goal: Check if radiation effects depend on dose rate
- Dose rate ~ 36 kRad/h, similar to dose rate of HL-LHC at 3cm from the interaction point
- Controlled temperature
- Constant monitoring and running tests, daily qualifications
- Targeting to accumulate several tens of Mrad
- Compare the results to high dose-rate tests



Setup at the irradiation chamber

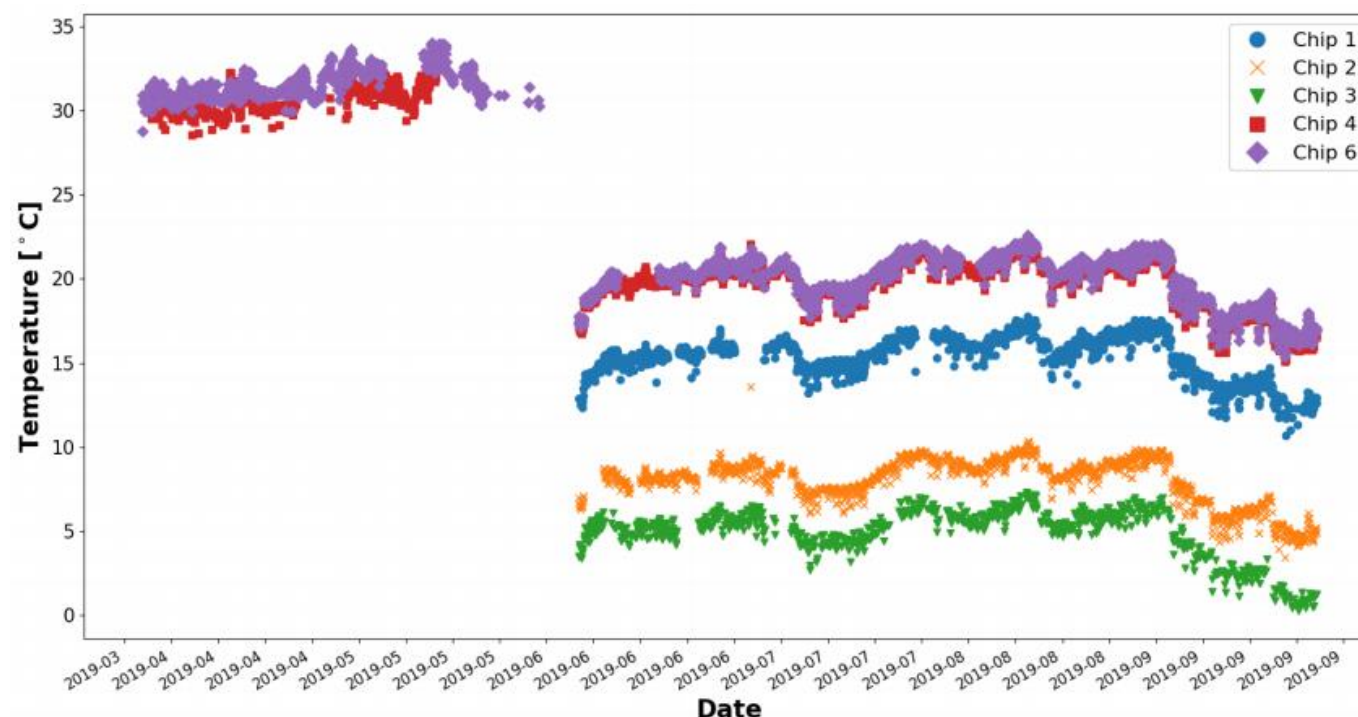
- Bottom box cooled with chiller, top box with chiller + Peltiers
- 3 SCCs per box, each SCC powered by a PSU in the control room and connected with a display port cable to its FPGA outside the irradiation chamber
- Room temperature chips at 20° C, cold chips at 5° C



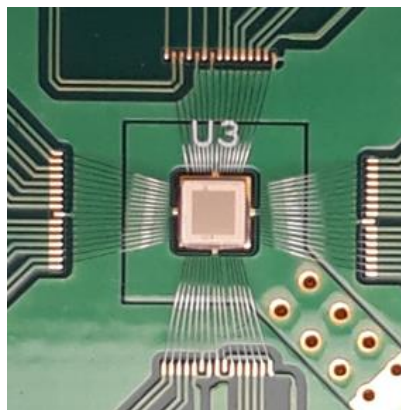
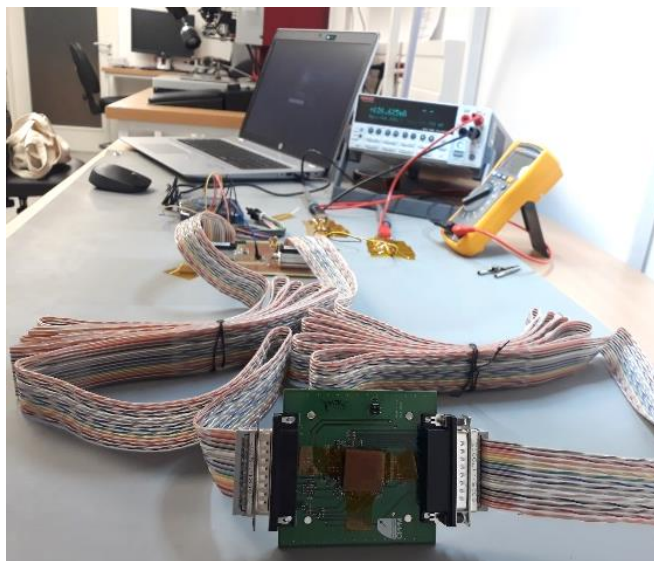


Comparison of the InverterClock ring oscillator structure with driving strength 0 (a) and driving strength 4 (b). Ring oscillator frequency is normalized to unity at the start of irradiation. Fluctuations in the frequency originate from temperature fluctuations.

[Low dose rate ⁶⁰Co facility in Zagreb](#), M. Roguljić



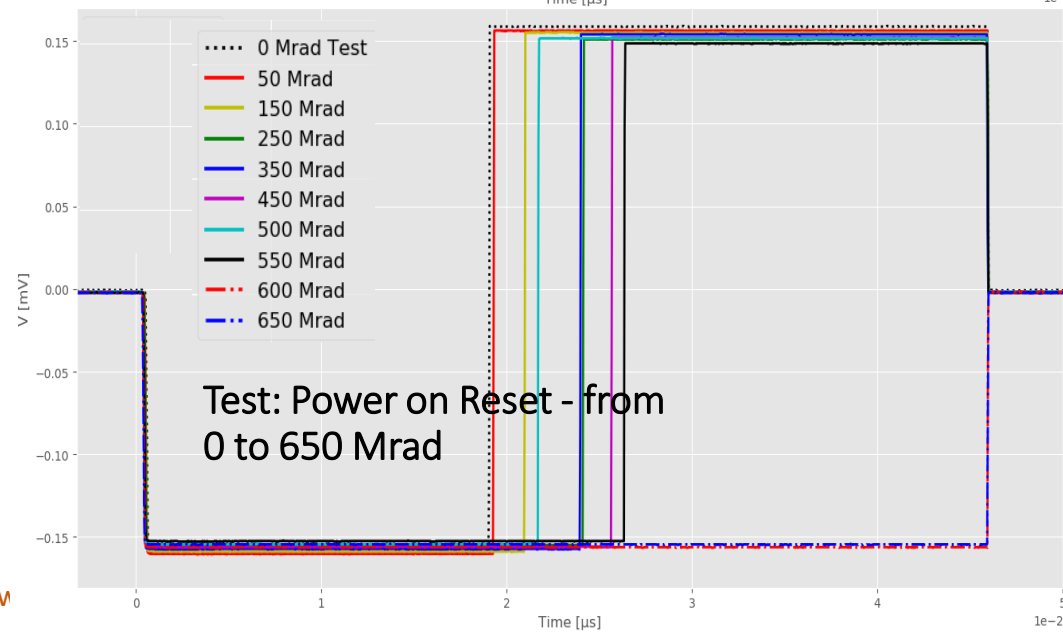
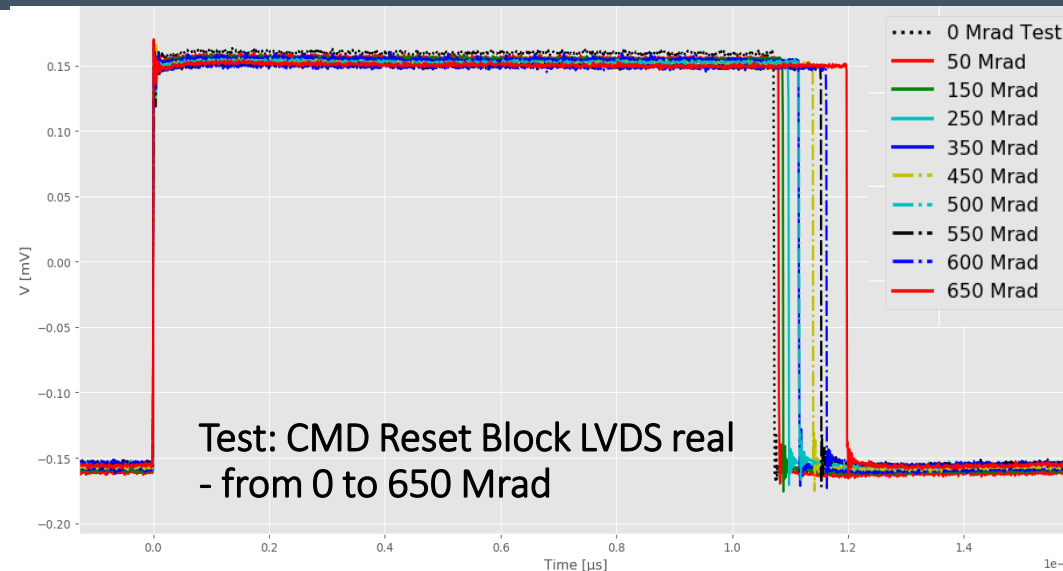
Temperature for chips cooled with Peltiers (1-3) and two chips without Peltier cooling (4 and 6).

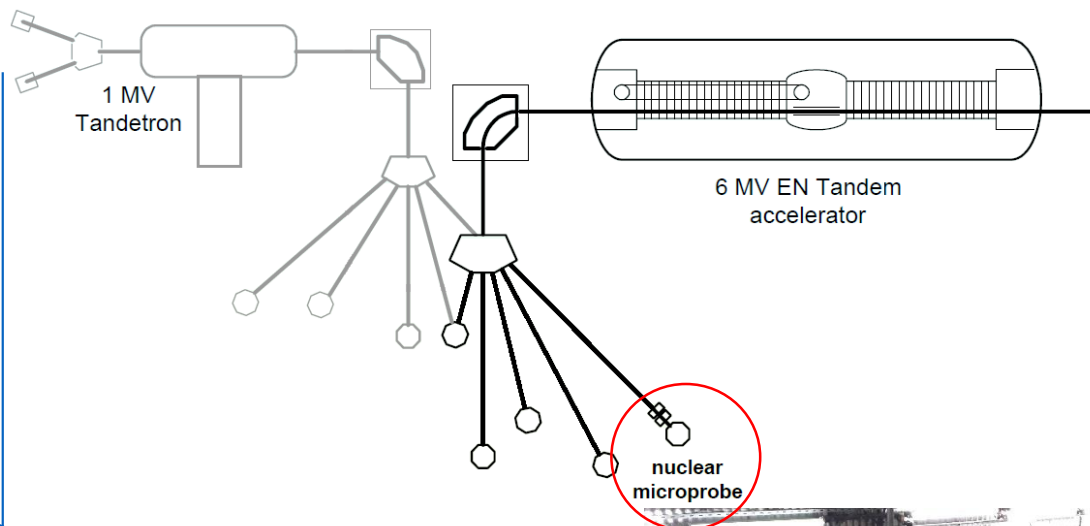


Goals and Tasks

- Goal: Confirm the designed 550 Mrad TID
- Dose rate ~ 2.37 Mad/h
- Both the chip's irradiation and measurements were performed at room temperature
- Due to annealing we observed a partial recovery in both circuits.
- * **RBI was closed due to COVID 19 lockdown** for 43 days

Aneliya Karadzhinova-Ferrer, 37th RD50 v





Nuclear Microprobe

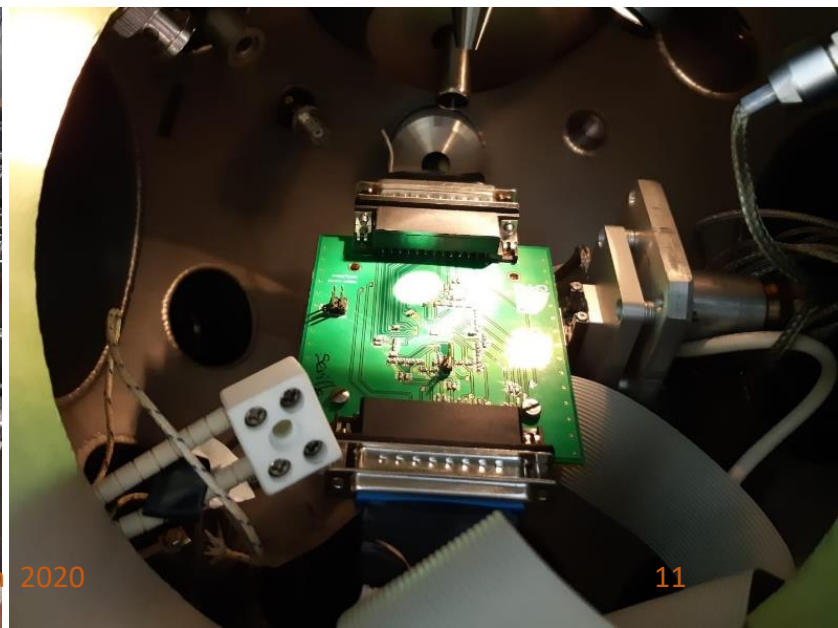
- Two accelerators, 6.0 MV Tandem Van de Graaff and 1.0 MV Tandatron
- Protons (0.4 to 8 MeV), Ions up to ME/q^2 ratio of 25 MeV
- Beam spot size can be as low as 250 nm, in normal use ~ few μm
- Scanning area from 1.5 mm down to a few μm

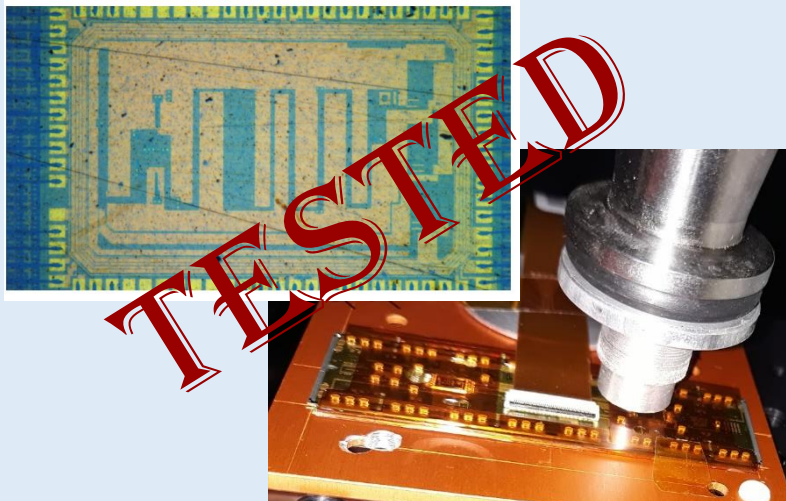
Other existing beam lines of EN Tandem accelerator:

- IAEA beam line - routine PIXE/RBS
- TOF ERDA
- Nuclear reactions chamber
- High resolution PIXE / ion implant.



Aneliya Karadzhinova-Ferrer, 37th RD50 workshop, Nov 19th 2020





TESTED

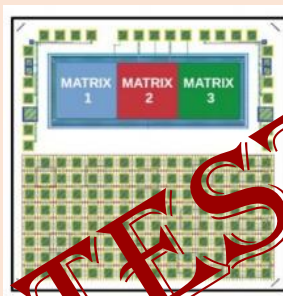
TBM Chip for CMS Pixel module

May and July 2019

H¹⁺ 6 MeV (LET= 0.05 MeV-cm²/mg)

Li⁷⁺ 4 MeV (LET= 1.73 MeV-cm²/mg)

C⁵⁺ 12 MeV (LET= 4.47 MeV-cm²/mg)



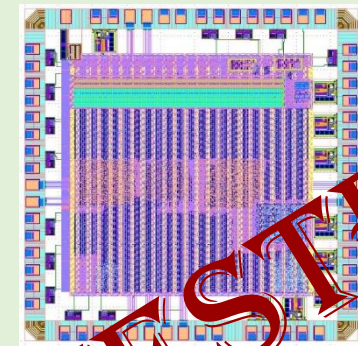
TESTED

Pseudo Matrix Test Chip

August 2019

H¹⁺ 2 MeV (LET=0.11 MeV-cm²/mg)

Fully Depleted MAPS in 110-nm CMOS Process
With 100–300-μm Active Substrate,
DOI: [10.1109/TED.2020.2985639](https://doi.org/10.1109/TED.2020.2985639)



TESTED

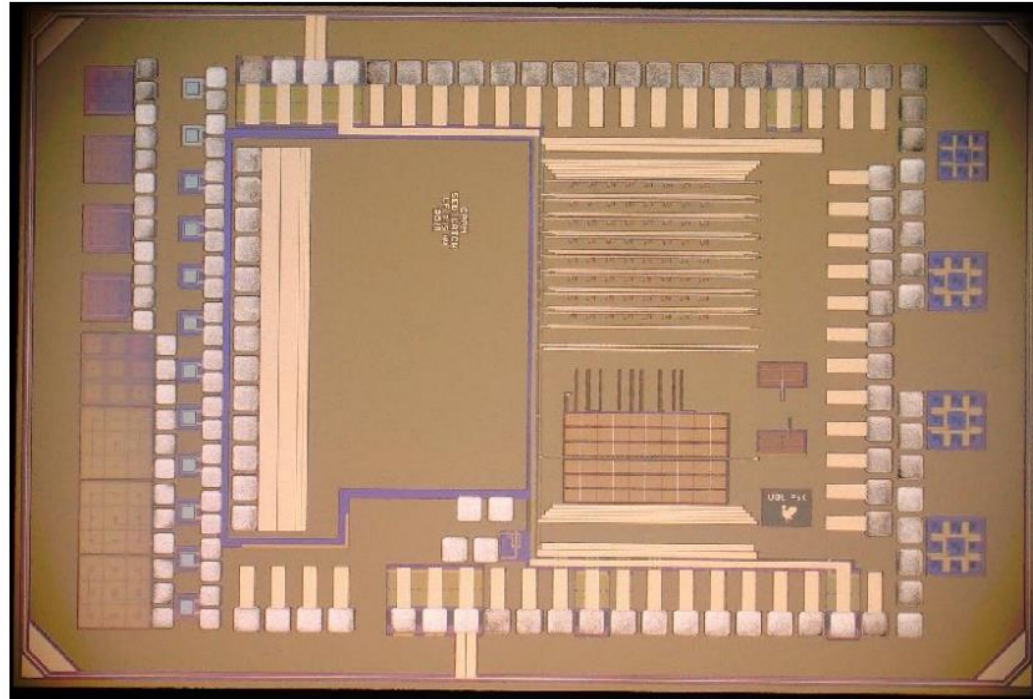
RD53SEU Test Chip

August 2019

Li³⁺ 9 MeV (LET=1.26 MeV-cm²/mg)

C⁵⁺ 14.6 MeV (LET=4.22 MeV-cm²/mg)

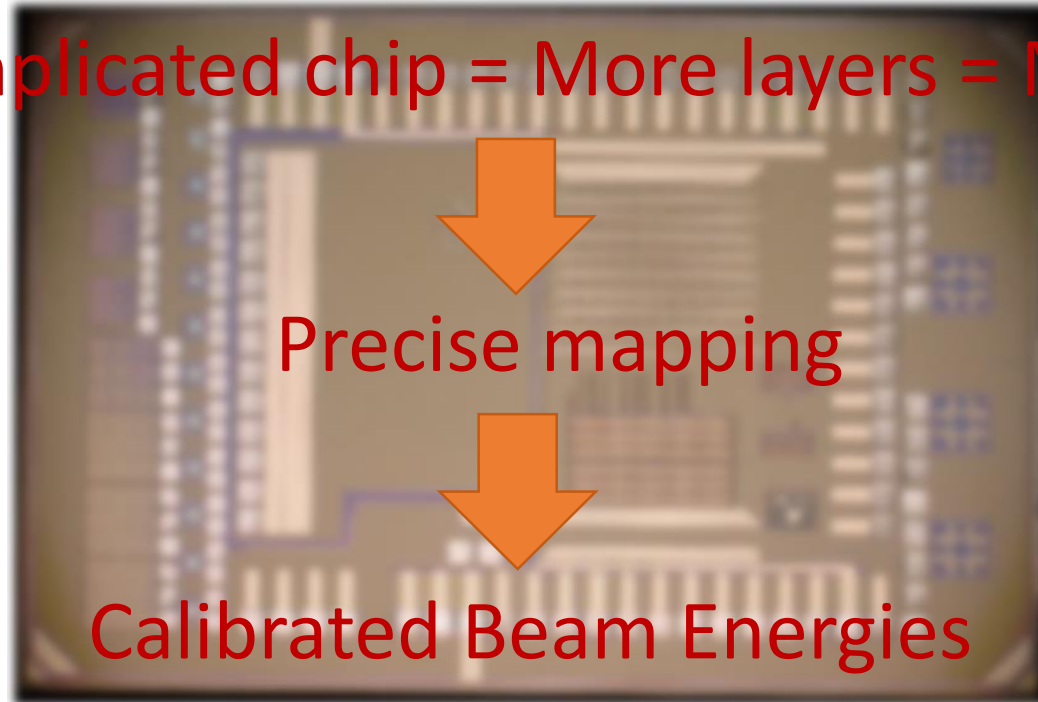
WANTED



RD50 – HVCMOS MPW2 Chip

WANTED

More complicated chip = More layers = More features



RD50 – HVCMOS MPW2 Chip

Which is the expected LET_{max} at LHC?

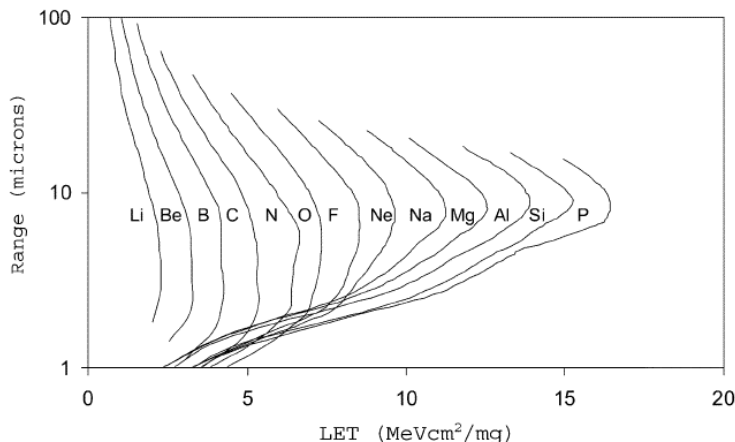


Fig. 1. Range versus LET of nuclei produced by protons in silicon.

LET Spectra of Proton Energy Levels From 50 to 500 MeV and Their Effectiveness for Single Event Effects Characterization of Microelectronics, David Hiemstra and Ewart Blackmore, DOI: [10.1109/TNS.2003.821811](https://doi.org/10.1109/TNS.2003.821811)

- ✓ SEU rates in LHC will in most devices be dominated by hadrons with $E > 20 \text{ MeV}$. It is reasonable to assume in the estimate that all hadrons above 20 MeV have the same effect
- ✓ To estimate error rates in LHC, use proton beams of 60-200 MeV to measure the cross-section of the circuits. Multiply the measured s for the flux of hadrons with $E > 20 \text{ MeV}$ in the location where the circuit has to work. This procedure has been adopted by all LHC experiments as a “standard” for circuit qualification
- ✓ A useful information to situate the sensitivity of circuits in the LHC is the maximum LET of recoils from nuclear interaction of hadrons with the Si nuclei. The maximum LET is for a Si recoil and the LET is about $15 \text{ MeVcm}^2\text{mg}^{-1}$. This information can be used to judge if a circuit for which Heavy Ion data is available will experience a high error rate in the LHC.

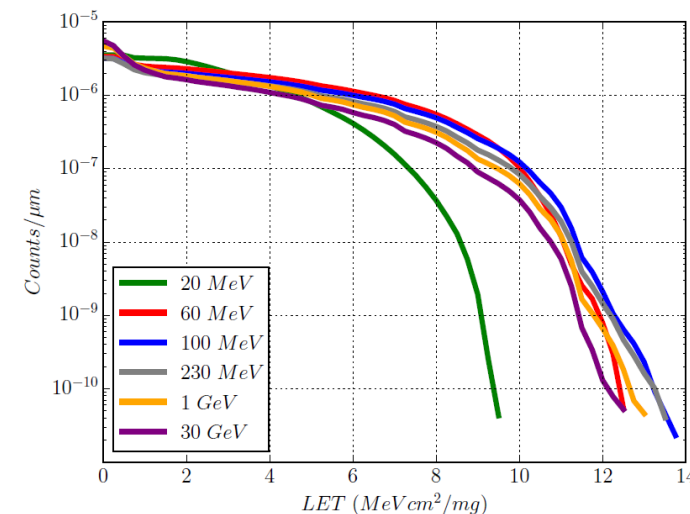


Fig. 4.8. LET reverse integral of the inelastic products ($Z \geq 2$, $E_{kin} > 100 \text{ keV}$) generated in proton-silicon interactions using the FLUKA production code. Results are normalized to the inelastic interaction cross section divided by the atom density.

Radiation Fields in High Energy Accelerators and their impact on Single Event Effects, [PhD Thesis](#) of Rubén GARCÍA ALÍA,

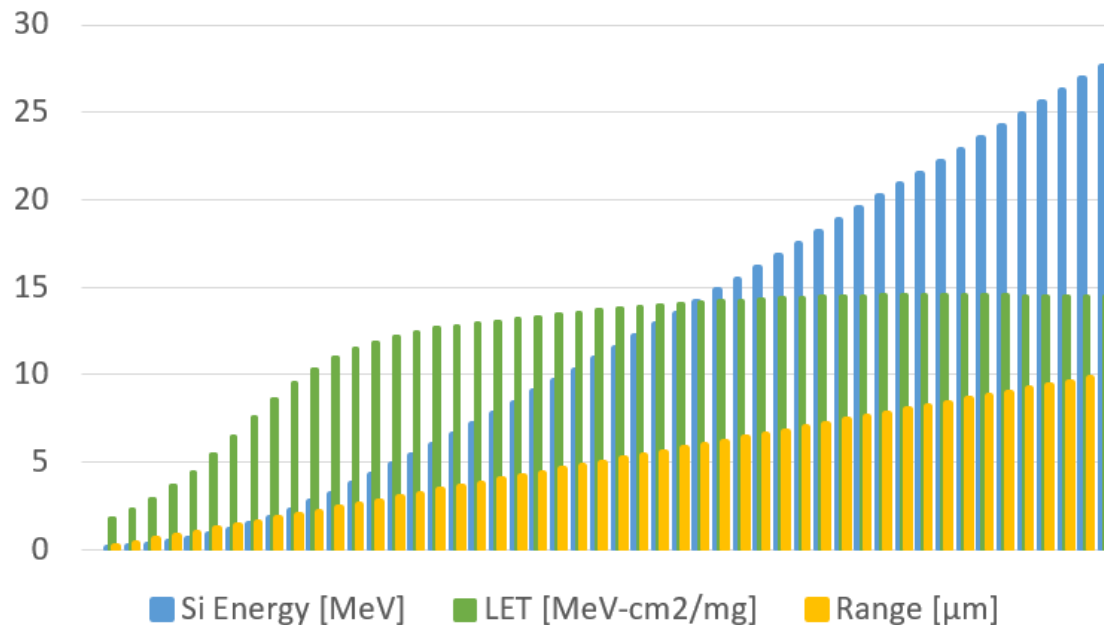
Goals and Tasks

- Verify the ion panoplia and energies available
- LET calculations to define the desired energies
- Preliminary SRIM simulations of the experimental setup
- Experimental measurements with several ion panoplia and energies

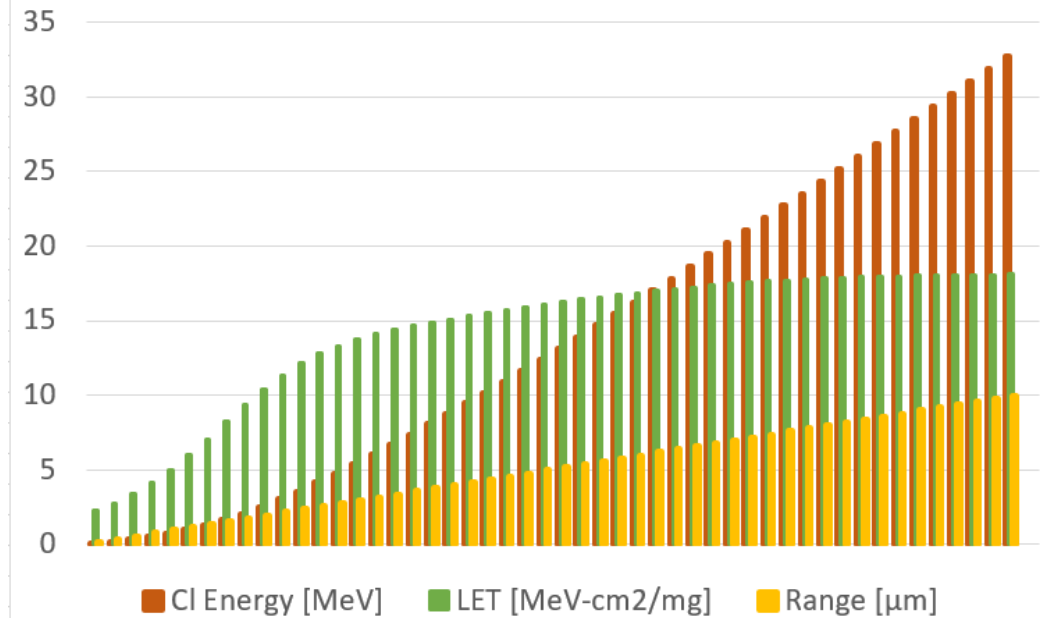


LET_{MAX} for LHC is
15 MeV-cm²/mg

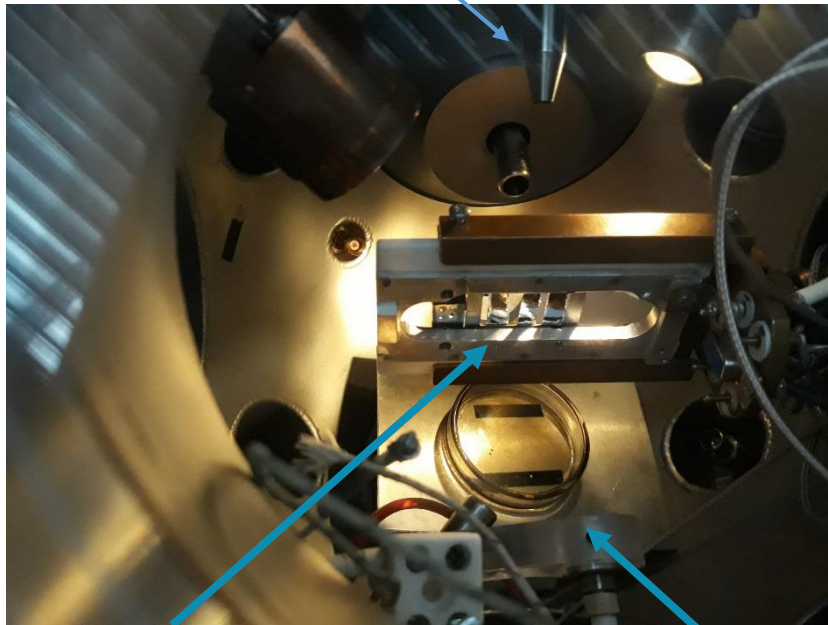
Si beam into Si target



Cl beam into Si target



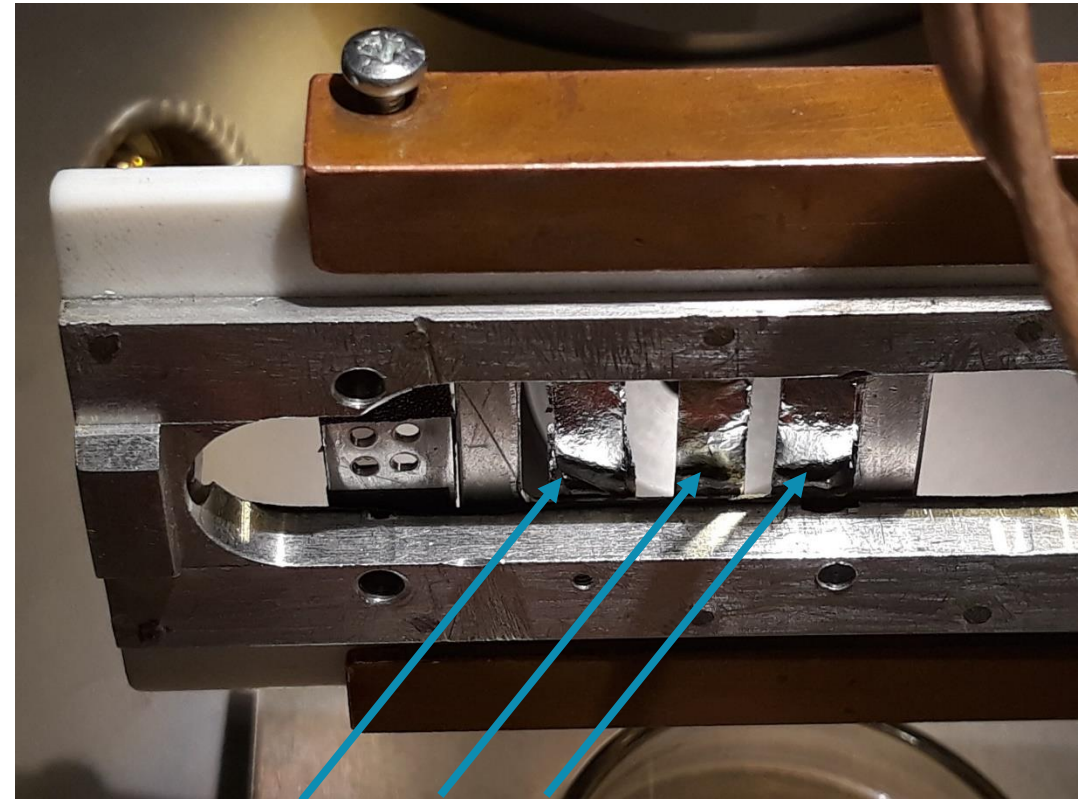
Microbeam Outlet



Targets of Al foil with different thickness

STIM detector

Microprobe chamber

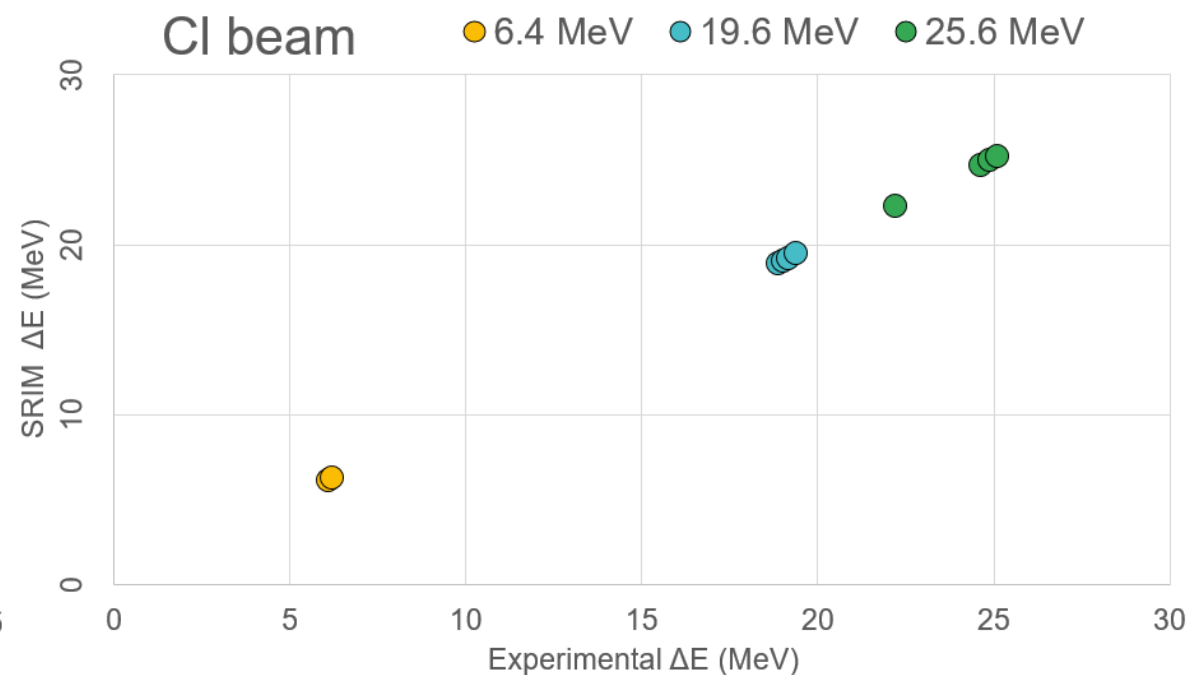
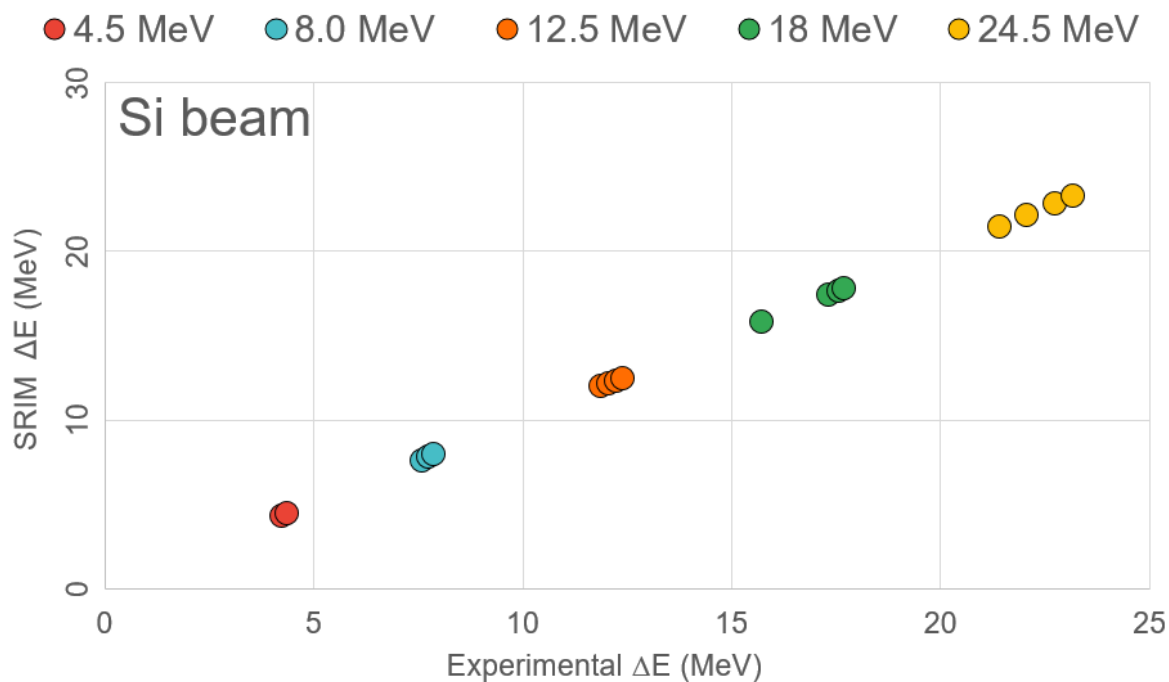


Targets of Al foil with thickness of 2, 3 and 5 μm (from left to right, respectively)

The following ion panoply and energies were selected based on the preliminary studies and the available sources

- Si => 3⁺, 4⁺, 5⁺, 6⁺ and 7⁺ (LET= 11.98 – 14.51 MeV-cm²/mg)
- Cl => 3⁺, 7⁺ and 8⁺ (LET= 14.27 – 17.90 MeV-cm²/mg)

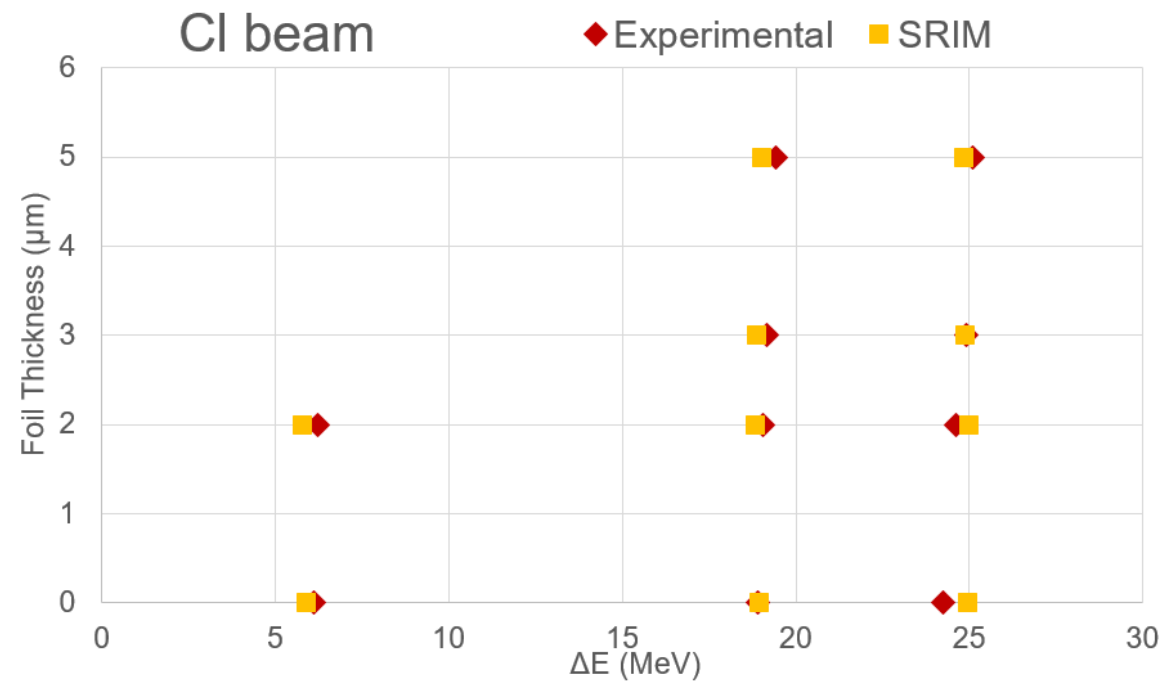
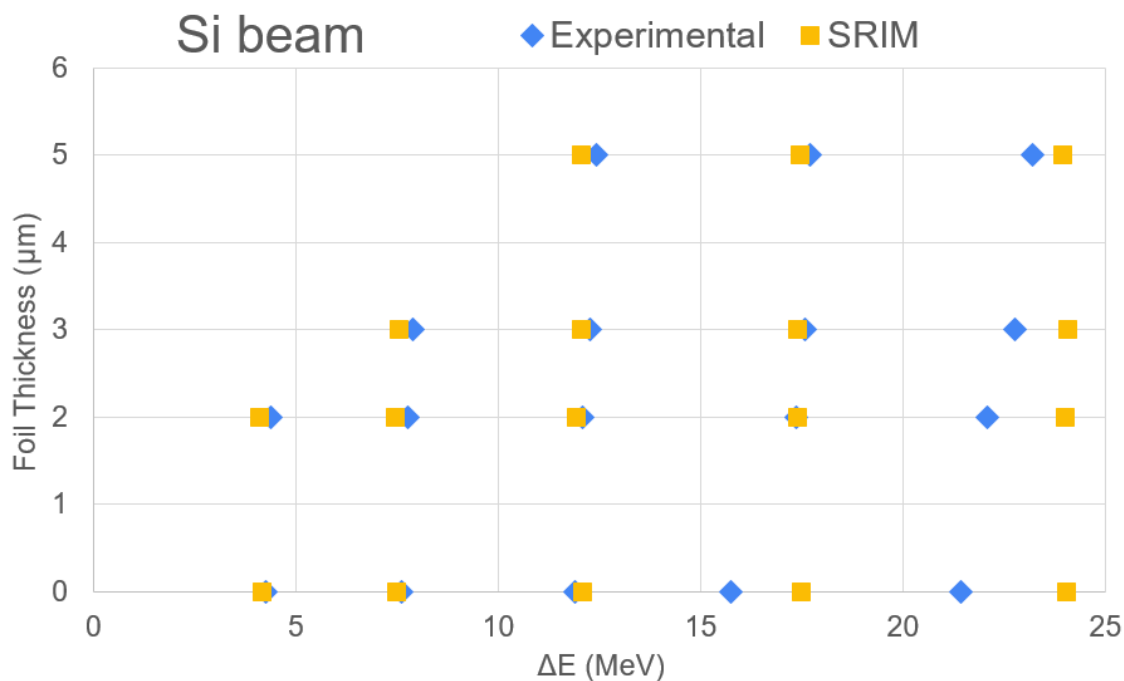
The experimental results were compared to SRIM simulation



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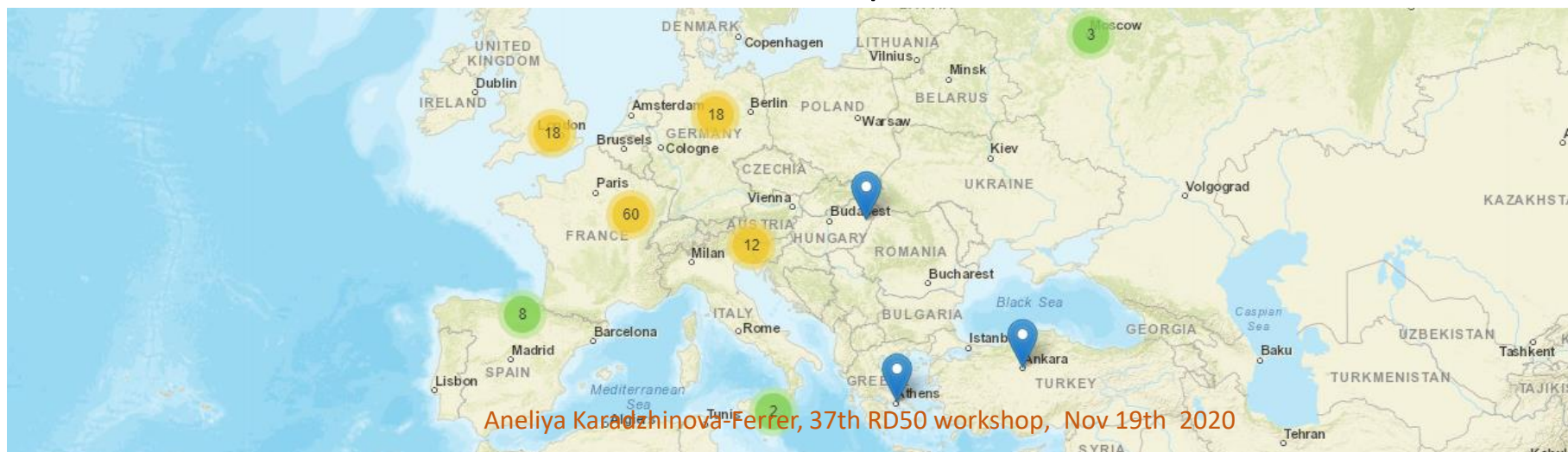
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The experimental results were compared to SRIM simulation



RBI has unique facilities for characterization of advanced detector and electronic devices

- ❑ The ^{60}Co irradiation facility already has experience and had already delivered the required irradiation on Phase 2 HDI samples, PROCV4 chips, Pixel Modules, PROC600 chips, RD53A chips, RD53SEU chip and more
- ❑ Proven results with Low Dose Rate and Total Ionization Dose studies
- ❑ Improvements to the atmospheric quality inside the Irradiation chamber are ongoing
- ❑ Soon to be add to the CERN irradiation facilities map



RBI has unique facilities for characterization of advanced detector and electronic devices

- The Ion Beam facility have performed Sensitivity mapping of various devices, such as the RD53SEU Test chip, the CMS TBM Functional chip and the Monolithic ARCADIA chip
- The LET certification to be continued with specifically designed calibration chip with several metallization layers
- We are looking forward of having RD50 HVCMOS MWP2 chip for SEE Sensitivity mapping tests at the IBA Microprobe
- [RADIATE](#) Transnational Access

Thank you for your attention!



This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 669014. The content on this website is the sole responsibility of the RBI and can in no way be taken to reflect the views of the European Union.

Backup slides





Dosimetry

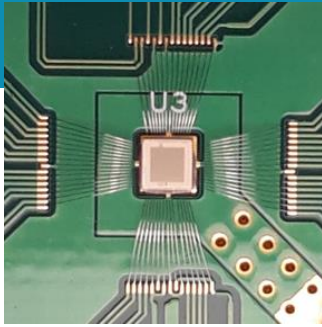
- Dose rates measured in several locations and verified with Geant4 simulation
- Ethanol-chlorobenzene dosimeters placed outside the box, in front of the chips
- Dose rates: Cold chips at 32 kRad/h, Room temperature chips at 36 kRad/h

Setup outside

- FPGAs on top of the concrete wall separating the corridor from the irradiation chamber, protected from radiation
- Connected by a 5m display port cable to the SCCs
- Cables and pipes routed through the corridor

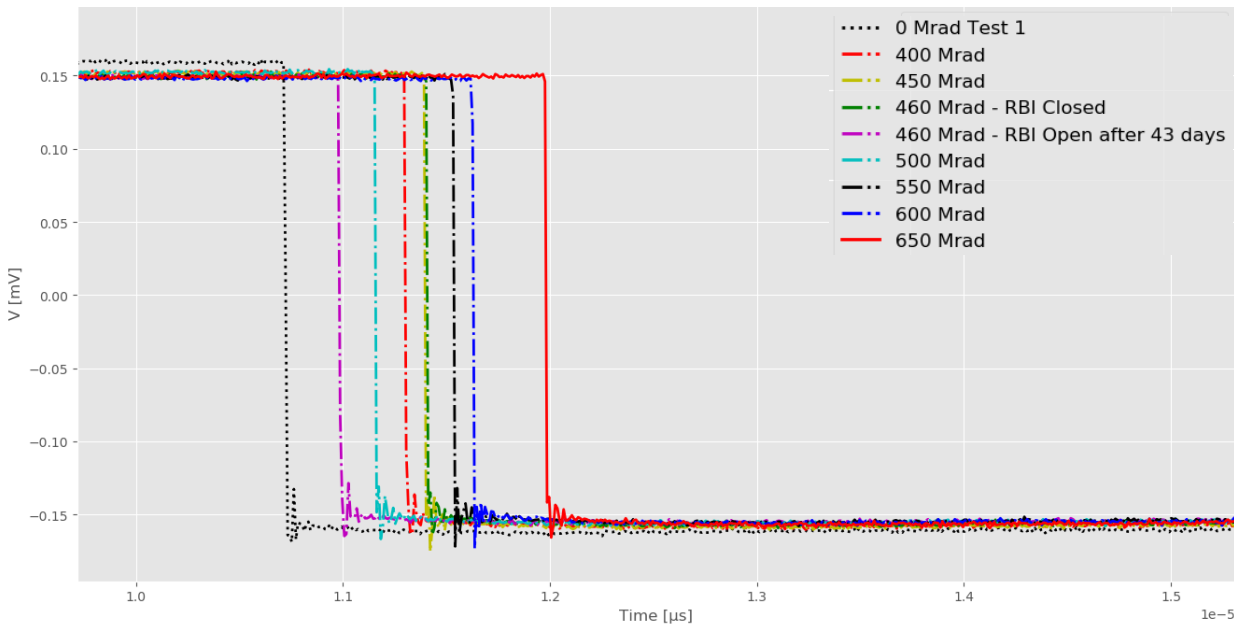


RD53SEU Chip



Impact of the RBI shutdown due to COVID 19

Test: CMD Reset Block LVDS real - from 0 to 650 Mrad



Shortly after 450 Mrad RBI went into shutdown, the chip was taken out of the irradiation chamber and stored at room temperature for 43 days

Test: Power on Reset - from 0 to 550 Mrad

